RUGGED HIGH-SPEED SOCKET

Board Mates: ERM8

Cable Mates: ERCD, ERDP

Robust Edge Rate® contact improves “Zippered” unmating 10 to 150 I/Os

Specifications
For complete specifications and recommended PCB layouts see www.samtec.com/ER8

Insulator Material: Black LCP
Contact Material: BeCu
Plating: Au or Sn over 50 µ” (1.27 µm) Ni
Current Rating: 2.2 A per pin (1 pin powered per row)
Operating Temp Range: -55 °C to + 125 °C
Voltage Rating: 225 VAC / 318 VDC
RoHS Compliant: Yes

Processing
Lead–Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004” max (005-030) (0.12 mm) .005” max (040-060) (0.15 mm) .006” max (070-100)

Recognitions
For complete scope of recognitions see www.samtec.com/quality

Protocols
• 100 GbE
• PCI Express™

Applications
For complete specifications and recommended PCB layouts see www.samtec.com/ER8

Electronic Applications
NEXUS5001™.org
POWER.org™

10 ASP-148421-01 ERF8–DV
11 ASP-137969-01 ERF8–DV
17 ASP-137973-01 ERF8–DV
20 ASP-133638-01 ERCD–DV
23 ASP-148422-01 ERF8–DV
25 ASP-135029-01 ERF8–DV
30 ASP-148424-01 ERF8–DV

Also Available (MOQ Required)
• Mezzanine stack heights
Contact Samtec.

Note: Patented
Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec’s specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.